

12345678910

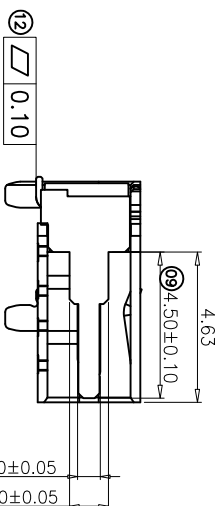
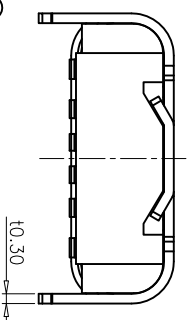
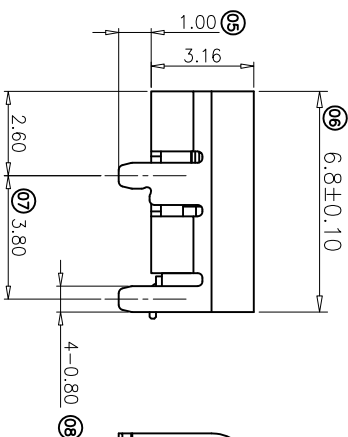
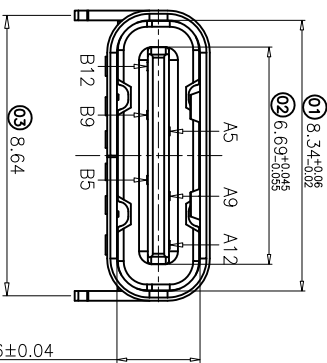
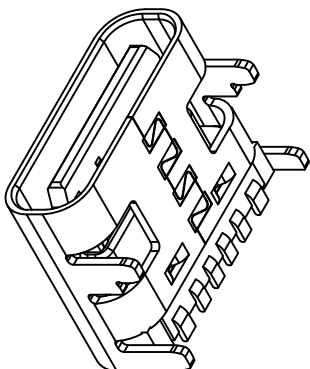
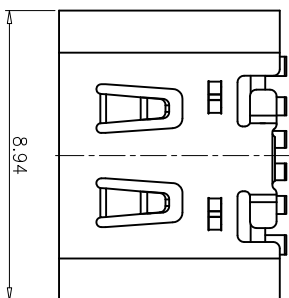
RoHS

MAPX

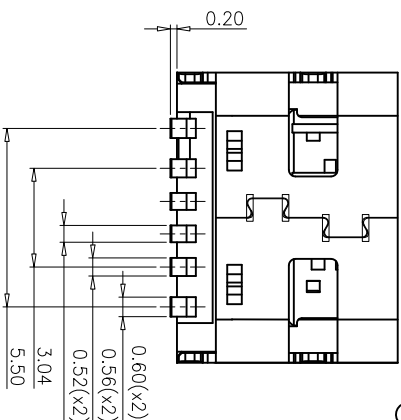
MODIFICATION

DRW

DATE



SECTION:A-A



NOTE1:

1.MATERIAL SPECIFICATION:

1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.

2.CONTACTS:COPPER ALLOY

3.MID PLATE: STAINLESS STEEL

4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

NI 50u" MIN. UNDER PLATED OVER ALL.

AU PLATED ON THE FUNCTIONAL AREA OF CONTACT.

(GOLD PLATING THICKNESS FOLLOW THE P/N)

PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

SEE TABLE1.

2-3.SHIELD PLATE&EMI PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

3-1.INSERTION FORCE: 0.5~2.0kgf.

3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.

3-3.DURABILITY: 2000 CYCLES.

4.ELECTRICAL PERFORMANCE,

4-1. CURRENT RATING:5.0A

VOLTAGE RATING:5.0V

4-2. LCCR:

VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.

SHIELD: 50mΩ/MAX.

LCCR MAX. CHANGE OF ALL PINS: 10mΩ.

4-3.INSULATION RESISTANCE: 100MΩ MIN

4-4.DIELECTRIC WITHSTAND VOLTAGE:AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL

BE MAINTAINED FOR 10 SECONDS AT 260°C.

7.COMPLY WITH RoHS 2.0 AND REACH AND OTHER ENVIRONMENTAL

PROTECTION REQUIREMENTS

产品图

公差一览表

TOLERANCE UNLESS OTHERWISE

X ±0.25 X ±5°

X ±0.20 X ±2°

XX ±0.05 XX ±1°

XXX ±0.02 XXX ±0.5°

深圳市精拓金电子有限公司
Shenzhen Jing Tuo Jin Electronics Co., Ltd.单位
MM比例
1:1日期
2020-05-22

DATE

审核
郭治富核准
黄国荣制图料号
918-418K2023S40044产品名称
TYPE-C3.1母座6.8四脚1.0插板PRODUCT NO
6.69/8.64有弹单排LCP黑胶SMT 6PIN角法
VER版本
AD